







APPLICABLE STANDARD					
Rating	Operating Temperature Range	-40 °C to 140 °C ⁽¹⁾	Storage Temperature Range	-10 °C to 60 °C ⁽²⁾	
	Voltage	125 V AC ⁽³⁾	Storage Humidity Range	Relative humidity 60% max (Not dewed)	
	Current	0.5 A	Operating Humidity Range	Relative humidity 85% max (Not dewed)	
SPECIFICATIONS					
ITEM	TEST METHOD		REQUIREMENTS	QT	AT
CONSTRUCTION					
General Examination	Examined visually and with a measuring instrument.		According to the drawing.	x	x
Marking	Confirmed visually.			x	x
ELECTRICAL CHARACTERISTICS					
Contact Resistance	Measured at 100 mA MAX.(DC or 1000Hz)		65mΩ MAX.	x	-
Insulation Resistance	Measured at 250 V DC.		1000 MΩ MIN.	x	-
Voltage Proof	375 V AC applied for 1 min.		No flashover or breakdown.	x	-
MECHANICAL CHARACTERISTICS					
Mating and Unmating Forces	Measured with an applicable connector.		Mating Force: 20 N MAX. Unmating Force: 2.2 N MIN.	x	-
Mechanical Operation	Mated and unmated 10 times.		①Contact Resistance : 75mΩ MAX. ②No damage, cracks or looseness of parts.	x	-
Vibration	Frequency 50~100 → 100~150 → 150~300Hz Acceleration 98 → 98~294 → 294 m/s ² 1 cycle 3 min 3 h for 3 axial directions ⁽⁴⁾		①No electrical discontinuity of more than 1 μs. ②No damage, cracks or looseness of parts.	x	-
Shock	Acceleration 980 m/s ² , duration of pulse 6 ms at 3 times for 3 axial directions.			x	-
ENVIRONMENTAL CHARACTERISTICS					
Damp Heat (Steady state)	Exposed at 60±2 °C, 90 ~ 95 %, 1000 h.		①Contact Resistance : 75mΩ MAX. ②Insulation Resistance : 1000 MΩ MIN. 	x	-
Rapid Change of Temperature	Temperature -40 → +140 °C Time 30 → 30 min. under 1000 cycles. (Relocation time to chamber : within 2~3 MIN)		③No damage, cracks or looseness of parts.	x	-
Cold	Exposed at -40°C, 1000 h		①Contact Resistance : 75mΩ MAX.	x	-
Dry Heat	Exposed at 140°C, 1000 h		②No damage, cracks or looseness of parts.	x	-
Sulfur Dioxide	Exposed at 40±2°C, 80±5%RH, 25±5ppm  for 96 h.		Contact Resistance : 75mΩ MAX.	x	-
Resistance to Soldering Heat	1)Reflow soldering : Peak TMP : 260°C MAX Reflow TMP: 220°C MIN for 60sec 		No deformation of case of excessive looseness of the terminal.	x	-
Solderability	Soldered at solder temperature 240±3°C for immersion duration, 3 sec.		A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.	x	-
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
	1	DIS-F-00016361	TK. ABE	HH. SHINDO	20221215
Notes			APPROVED	HH. SHINDO	20191007
(1) Include temperature rise caused by current-carrying.			CHECKED	KN. SHIBUYA	20191007
(2) "STORAGE" means a long-term storage state for the unused product before assembly to PCB.			DESIGNED	TK. ABE	20191007
(3) The creepage distance conforms to IEC 60664-1. Voltage effective value: 32V AC, Pollution Degree: 2			DRAWN	KI. YAMAZAKI	20191007
(4) Amplitude between connector mounting part and PCB is 0.05mm MAX.					
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.	ELC-376648-00-00	
	SPECIFICATION SHEET		PART NO.	FX26-20S-1SV20	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL0576-1302-0-00	 1/1